Number	L	Hits	Search Text	DB	Time stamp
		465825	(stack stacking stacked stackable	IISPAT.	2004/09/06
Tadiate radiation radiating radiated dissipation dissipating dissipated dissipate slug) same (stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated ad) circuit)) 16:26 1877 1877 1878	1	463623	multiple level plurality) with (substrate semiconductor die dice ic chip	US-PGPUB; EPO; JPO; DERWENT;)
19382	2	352735	radiate radiation radiating radiated dissipation dissipating dissipated	USPAT; US-PGPUB; EPO; JPO; DERWENT;	
radiate radiation radiating radiated dissipated dissipated dissipated stacked stackable multiple level plurality) with (substrate semiconductor circuit)) 1317 (epoxy mold moulded molded encase encased encasing encapsulating encapsulatine encapsulated asimate (asisipate adiasing radiated dissipate adiasipation dissipating dissipated dissipate stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adjocircuit))) 6 380 (epoxy mold moulded molded encase encased encasing encapsulating radiated dissipation dissipating dissipated dissipate adjocircuit))) 6 (epoxy mold moulded molded encase encased encasing encapsulating encapsulating encapsulating encapsulate encapsulated with ((heat with (substrate semiconductor die dice ic chip (integrated adjocircuit))) 8 (epoxy mold moulded molded encase encased encasing encapsulating encapsulate encapsulate encapsulating radiated dissipation dissipation dissipation) 8 (epoxy mold moulded molded encase encased encasing encapsulating encapsulate) 9 (epoxy mold moulded molded encase encased encased encasing encapsulation encapsulate) 10 (epoxy mold moulded molded encase encased encased encasing encapsulation encapsulate) 11 (uspat) 12 (uspat) 13 (uspat) 14 (uspat) 15 (uspat) 16:27 16:27 16:27 16:27 16:28 16:28 16:28 100 105 105 105 105 105 107 107	3	9382	radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) same ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj	USPAT; US-PGPUB; EPO; JPO; DERWENT;	
	4	5412	radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) with ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj	US-PGPUB; EPO; JPO; DERWENT;	1
Sample	5	1317	encasing encapsulant encapsulate encapsulating encapsulation encapsulated) same ((heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) same ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj	US-PGPUB; EPO; JPO; DERWENT;	· · · ·
7 1 1 2004/09/06 16:34 8 1 1 USPAT 2004/09/06 16:34 9 1 USPAT 2004/09/06 16:34 10 1 USPAT 2004/09/06 16:34 11 1 1 1 USPAT 2004/09/06 16:35 12 1 USPAT 2004/09/06 16:35 13 1 USPAT 2004/09/06 16:35 14 1 USPAT 2004/09/06 16:35 15 1 USPAT 2004/09/06 16:35	6	380	(epoxy mold moulded molded encase encased encasing encapsulant encapsulate encapsulating encapsulation encapsulated) with ((heat with (sink cover lid stiffener radiate radiation radiating radiated dissipation dissipating dissipated dissipate slug)) with ((stack stacking stacked stackable multiple level plurality) with (substrate semiconductor die dice ic chip (integrated adj	US-PGPUB; EPO; JPO; DERWENT;	
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16:34 USPAT 2004/09/06 16:34 11		1		USPAT	2004/09/06 16:34
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24	1		USPAT	16:36 2004/09/06
25	1		USPAT	16:36 2004/09/06
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37	1		USPAT	2004/09/06 16:38
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49	1		USPAT	2004/09/06 16:40
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	_		OSIAI	16:41
54	1		USPAT	2004/09/06
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55	1		USPAT	2004/09/06
56	1		USPAT	16:41
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57	1		USPAT	2004/09/06
				16:41
58	1		USPAT	2004/09/06
				16:41
59	1		USPAT	2004/09/06
60	1		USPAT	16:41
	-			16:42
61	1		USPAT	2004/09/06
				16:42
62	1		USPAT	2004/09/06
63	1		USPAT	16:42 2004/09/06
03	_		USPAI	16:42
64	1		USPAT	2004/09/06
	ļ			16:42
65	1		USPAT	2004/09/06
66	1	,	USPAT	16:43 2004/09/06
			USPAI	16:43
67	937	((epoxy mold moulded molded encase	USPAT;	2004/09/06
		encased encasing encapsulant encapsulate	US-PGPUB;	16:53
		encapsulating encapsulation encapsulated)	EPO; JPO;	
		same ((heat with (sink cover lid	DERWENT;	
		stiffener radiate radiation radiating radiated dissipation dissipating	IBM_TDB	
		dissipated dissipate slug)) same ((stack		
		stacking stacked stackable multiple level		
		plurality) with (substrate semiconductor		
		die dice ic chip (integrated adj		
		circuit))))) not ((epoxy mold moulded		
		molded encase encased encasing encapsulant encapsulate encapsulating		
		encapsulation encapsulated) with ((heat		
		with (sink cover lid stiffener radiate		
	į	radiation radiating radiated dissipation		
	ļ	dissipating dissipated dissipate slug))		
		with ((stack stacking stacked stackable		
		multiple level plurality) with (substrate semiconductor die dice ic chip		
		(integrated adj circuit)))))		
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